UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.,

and

APPLE INC.,

Petitioners

v.

MYW SEMITECH, LLC,

Patent Owner

Inter Partes Review Case No. IPR2026-00066
U.S. Patent No. 11,538,763

PETITIONERS' UPDATED EXHIBIT LIST

APPENDIX OF EXHIBITS

Exhibit 1001	U.S. Patent No. 11,538,763
Exhibit 1002	File History of the ’763 Patent
Exhibit 1003	Declaration of Stanley Shanfield, Ph.D.
Exhibit 1004	U.S. Patent No. 9,167,694 to Sundaram, et al.
Exhibit 1005	U.S. Patent Publication No. 2010/0290191 to Lin, et al.
Exhibit 1006	U.S. Patent Publication No. 2011/0215458 to Camacho, et al.
Exhibit 1007	U.S. Patent No. 9,679,863 to Lin, et al.
Exhibit 1008	U.S. Patent Publication 2011/0266691 to Lin, et al.
Exhibit 1009	Intentionally left blank
Exhibit 1010	U.S. Patent No. 9,123,763 to Yu, et al.
Exhibit 1011	U.S. Patent Publication 2014/0035935 to Shenoy, et al.
Exhibit 1012	Andrea Chen, et al. *Semiconductor Packaging Materials Interaction and Reliability*, CRC Press, 2012
Exhibit 1013	Philip Garrou, et al., *RDL: an integral part of today’s advanced packaging technologies*, Solid State Technology, May 2011
Exhibit 1014	U.S. Patent No. 8,780,576 to Haba, et al.
Exhibit 1015	U.S. Patent No. 7,902,648 to Lee
Exhibit 1016	U.S. Patent No. 7,964,961 to Lee, et al.
Exhibit 1017	U.S. Patent No. 7,241,641 to Savastiouk, et al.
Exhibit 1018	U.S. Patent Publication No. 2005/0110168 to Chuang
Exhibit 1019	U.S. Patent Publication No. 2011/0026232 to Lin, et al.
Exhibit 1020	U.S. Patent No. 5,086,558 to Grube, et al.
Exhibit 1021	U.S. Patent Publication No. 2011/0193219 to Lai, et al.
Exhibit 1022	U.S. Patent No. 6,818,545 to Lee, et al.
Exhibit 1023	U.S. Patent No. 6,974,659 to Su, et al.
Exhibit 1024	U.S. Patent Publication No. 2006/0175686 to Murata, et al.
Exhibit 1025	U.S. Patent Publication No. 2012/0098124 to Wu, et al.
Exhibit 1026	U.S. Patent No. 8,193,604 to Lin et al.
Exhibit 1027	U.S. Patent Publication No. 2004/0203224 to Halahan, et al.
Exhibit 1028	Philip Garrou, *Introduction to 3D Integration,* Handbook of 3D integration: Volumes 1 and 2, Technology and Application of 3D Integrated Circuits, 2012
Exhibit 1029	U.S. Patent Publication No. 2003/0068877 to Kinsman
Exhibit 1030	U.S. Patent Publication No. 2010/0246152 to Lin, et al.
Exhibit 1031	Yi Yang, et al, *CPU-Assisted GPGPU on Fused CPU-GPU Architectures,* IEEE Xplore
Exhibit 1032	File History of U.S. Patent No. 11,107,768

Exhibit 1033	U.S. Patent No. 4,863,773 to Rousseau, et al.
Exhibit 1034	U.S. Patent No. 6,365,265 to Tose, et al.
Exhibit 1035	E.D. Blackshear, et al., *The evolution of build-up package technology and its design challenges*, International Business Machines Corporation, 2005
Exhibit 1036	Intentionally Left Blank
Exhibit 1037	U.S. Patent No. 7,374,969 to Cho, et al.
Exhibit 1038	U.S. Patent No. 7,199,036 to Chan, et al.
Exhibit 1039	U.S. Patent No. 8,158,508 to Lin, et al.
Exhibit 1040	U.S. Patent No. 6,619,538 to Test, et al.
Exhibit 1041	U.S. Patent Publication No. 2011/0101523 to Hwang, et al.
Exhibit 1042	U.S. Patent No. 6,831,003 to Huang, et al.
Exhibit 1043	U.S. Patent Publication No. 2009/0226611 to Suzuki, et al.
Exhibit 1044	U.S. Patent No. 6,077,726 to Mistry, et al.
Exhibit 1045	U.S. Patent Publication No. 2010/0244245 to Pendse, et al.
Exhibit 1046	U.S. Patent Publication No. 2012/0206160 to Wu, et al.
Exhibit 1047	U.S. Patent Publication No. 2009/0174052 to Sogawa, et al.
Exhibit 1048	U.S. Patent Publication No. 2013/0100624 to Carpenter, et al.
Exhibit 1049	U.S. Patent No. 7,047,515 to Vitek, et al.
Exhibit 1050	U.S. Patent No. 8,116,097 to Love, et al.
Exhibit 1051	U.S. Patent Publication No. 2009/0237900 to Origuchi, et al.
Exhibit 1052	U.S. Patent Publication No. 2005/0002167 to Hsuan, et al.
Exhibit 1053	U.S. Patent Publication No. 2008/0067695 to Chow, et al.
Exhibit 1054	U.S. Patent No. 6,489,240 to Iacoponi, et al.
Exhibit 1055	U.S. Patent No. 6,578,178 to Mau
Exhibit 1056	U.S. Patent Publication No. 2012/0001190 to Okabe, et al.
Exhibit 1057	U.S. Patent No. 7,307,348 to Wood, et al.
Exhibit 1058	U.S. Patent No. 8,138,014 to Chi, et al.
Exhibit 1059	U.S. Patent No. 6,506,672 to Dagenais, et al.
Exhibit 1060	U.S. Patent No. 8,518,798 to Graetz
Exhibit 1061	U.S. Patent Publication No. 2009/0261473 to Lee, et al.
Exhibit 1062	U.S. Patent No. 6,440,289 to Woo, et al.
Exhibit 1063	U.S. Patent No. 6,812,143 to Lane, et al.
Exhibit 1064	U.S. Patent Publication No. 2012/0145552 to Nagai, et al.
Exhibit 1065	U.S. Patent Publication No. 2011/0147950 to Tsi, et al.
Exhibit 1066	U.S. Patent Publication No. 2009/0070727 to Solomon
Exhibit 1067	U.S. Patent Publication No. 2012/0098114 to Ishibashi
Exhibit 1068	U.S. Patent Publication No. 2011/0074028 to Pendse
Exhibit 1069	U.S. Patent No. 7,485,955 to Kang, et al.

Exhibit 1070	U.S. Patent Publication No. 2012/0104623 to Pagaila, et al.
Exhibit 1071	Intentionally left blank
Exhibit 1072	U.S. Patent No. 7,772,880 to Solomon
Exhibit 1073	U.S. Patent No. 7,989,270 to Huang, et al.
Exhibit 1074	U.S. Patent Publication No. 2011/0304999 to Yu, et al
Exhibit 1075	U.S. Patent Publication No. 2009/0117327 to Takada
Exhibit 1076	U.S. Patent Publication No. 2005/0081744 to Klocke, et al.,
Exhibit 1077	U.S. Patent No. 6,291,082 to Lopatin
Exhibit 1078	Intentionally left blank
Exhibit 1079	Intentionally left blank
Exhibit 1080	U.S. Patent Publication No. 2012/0319251 to Yu, et al.
Exhibits 1081-1089	Intentionally left blank
Exhibit 1090	U.S. Patent Publication No. 2005/0156280 to Patel, et al.
Exhibits 1091-1092	Intentionally left blank
Exhibit 1093	U.S. Patent No. 6,107,180 to Munroe, et al.
Exhibit 1094	U.S. Patent Publication No. 2011/0210283 to Ramirez, et al.
Exhibit 1095	U.S. Patent No. 6,452,502 to Dishongh, et al.
Exhibit 1096	U.S. Patent No. 6,344,401 to Lam.
Exhibit 1097	Richard K. Ulrich, et al., *Advanced Electronic Packaging,* IEEE Press Series on Microelectrical Systems, 2006
Exhibit 1098	Mulugeta Abtew, et al., *Lead-free Solders in Microelectronics*, Materials Science and Engineering, 2000
Exhibit 1099	Karl J. Puttlitz, et al., *Handbook of Lead-Free Solder Technology for Microelectronic Assemblies*, 2005
Exhibit 1100	U.S. Patent Publication No. 2013/0309832 to Cheng, et al.
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Exhibit 1102	Linely Gwennap, *Sandy Bridge Spans Generations: Intel Focuses on Graphics, Multimedia in New Processor Design*, Microprocessor, 2010
Exhibit 1103	U.S. Patent No. 6,330,164 to Khandros, et al.
Exhibit 1104	U.S. Patent No. 6,710,447 to Nogami.
Exhibits 1105-1126	Intentionally left blank
Exhibit 1127	U.S. Patent No. 8,238,113 to Iihola, et al.
Exhibit 1128	Intentionally left blank
Exhibit 1129	U.S. Patent No. 6,468,413 to Fanti, et al.
Exhibit 1130	U.S. Patent No. 8,132,775 to Goldmann.

Exhibit 1131	U.S. Patent Publication No. 2011/0186977 to Chi, et al.
Exhibit 1132	U.S. Patent No. 7,169,627 to Duh, et al.
Exhibit 1133	U.S. Patent No. 6,614,243 to Klehn, et al.
Exhibit 1134	U.S. Patent Publication No. 2009/0162622 to Van Veen, et al.
Exhibit 1135	U.S. Patent No. 6,570,259 to Alcoe, et al.
Exhibit 1136	U.S. Patent No. 7,741,567 to Beddingfield, et al.
Exhibit 1137	U.S. Patent No. 6,407,341 to Anstrom, et al.
Exhibit 1138	Email to Patent Owner's Counsel with Stipulation
Exhibit 1139	Revision to Rules of Practice Before the Patent Trial and Appeal Board, 90 Fed. Reg. 48335 (Oct. 17, 2025) (to be codified at 37 CFR pt. 42)
Exhibit 1140	*MYW Semitech, LLC v. Apple Inc.*, No. 1:25-cv-00504, Dkt. 26, Scheduling Order (D. Del. Sept. 5, 2025)
Exhibit 1141	Left Intentionally Blank
Exhibit 1142	Left Intentionally Blank
Exhibit 1143	Left Intentionally Blank
Exhibit 1144	Left Intentionally Blank
Exhibit 1145	Apple iPhone 7 Introduction Press Release, dated Sept. 7, 2016
Exhibit 1146	*MYW Semitech, LLC v. Apple Inc.*, No. 1:25-cv-00504, Dkt. 18, Amended Complaint (D. Del. July 7, 2025)
Exhibit 1147	*MYW Semitech, LLC v. Apple Inc.*, No. 1:25-cv-00504, Dkt. 83, Order (D. Del. Feb. 12, 2026) ("Semitech Order")
Exhibit 1148	*MYW Semitech, LLC v. Apple Inc.*, No. 1:25-cv-00504, Hearing Transcript (D. Del. Feb. 12, 2026) ("Hearing Transcript")
Exhibit 1149	*MYW Semitech, LLC v. Apple Inc.*, No. 1:25-cv-00504, Dkt. 87, Apple's Responsive Letter (D. Del. Feb. 13, 2025)
Exhibit 1150	Docket Navigator's Statistics for Judge Andrew's Motion for Stay Pending IPR (Post-Institution) Success
Exhibit 1151	Chief Administrative Patent Judge Boalick's Memorandum dated March 24, 2025
Exhibit 1152	CNBC Transcript: United States Commerce Secretary Howard Lutnick Speaks with CNBC's Brian Sullivan on "The Exchange" Today, CNBC (Apr. 29. 2025), available at https://www.cnbc.com/2025/04/29/cnbc-transcript-united-states-commerce-secretary-howard-lutnick-speaks-with-cnbcs-brian-sullivan-on-the-exchange-today.html
Exhibit 1153	Trump on China Putting - America First (Robert C. O'Brien editor)
Exhibit 1154	Remarks: Donald Trump Announces an Economic Investment in the United States - March 3, 2025, available at

	https://rollcall.com/factbase/trump/transcript/donald-trump-remarks-economic-investment-united-states-march-3-2025/#2
Exhibit 1155	Speech: Donald Trump Addresses an Republican Dinner in Washington - April 8, 2025, available at https://rollcall.com/factbase/trump/transcript/donald-trump-speech-nrcc-republican-dinner-april-8-2025/#161
Exhibit 1156	Another Historic Investment Secured Under President Trump, Articles, The White House (Mar. 3, 2025), available at https://www.whitehouse.gov/articles/2025/03/another-historic-investment-secured-under-president-trump/
Exhibit 1157	Jeremy Bowman, Nasdaq, This 1 Number May Ensure TSMC's Market Dominance, The Motley Fool (Aug. 17, 2024), available at https://www.nasdaq.com/articles/1-number-may-ensure-tsmcs-market-dominance
Exhibit 1158	TSMC Arizona Webpage, available at https://www.tsmc.com/static/abouttsmcaz/index.htm
Exhibit 1159	Silvia Pellegrino, What is TSMC?, Tech Monitor (Jan. 2, 2023), available at https://www.techmonitor.ai/what-is/what-is-tsmc/?cf-view
Exhibit 1160	U.S. Patent No. 11,107,768 to Yang
Exhibit 1161	U.S. Patent No. 8,709,933 to Haba, et al.
Exhibit 1162	*MYW Semitech, LLC v. Apple Inc.*, Case No. 1:25-cv-00504, Dkt. 118, Order to Stay (D. Del. June 16, 2026)

Respectfully submitted,

ERISE IP, P.A.

BY: /s/ Jennifer C. Bailey

Jennifer C. Bailey, Reg. No. 52,583
jennifer.bailey@eriseip.com
7015 College Boulevard, Suite 700
Overland Park, Kansas 66211
(913) 777-5600 Telephone
(913) 777-5601 Facsimile

COUNSEL FOR PETITIONERS,

TAIWAN SEMICONDUCTOR
MANUFACTURING COMPANY LTD. AND
APPLE INC.

CERTIFICATE OF SERVICE ON PATENT OWNER
UNDER 37 C.F.R. § 42.105

Pursuant to 37 C.F.R. §§ 42.6(e) and 42.105(b), the undersigned certifies that on June 22, 2026, a complete and entire copy of this *Petitioners' Updated Exhibit* and Exhibits was served via electronic filing with the Board and via Electronic Mail on the following practitioners of record for Patent Owner:

djackson@daignaultiyer.com
rjuang@daignaultiyer.com
cbiyer@daignaultiyer.com
rdaignault@daignaultiyer.com
ehadi@daignaultiyer.com

Respectfully submitted,

ERISE IP, P.A.

BY: /s/ Jennifer C. Bailey

Jennifer C. Bailey, Reg. No. 52,583
jennifer.bailey@eriseip.com
7015 College Boulevard, Suite 700
Overland Park, Kansas 66211
(913) 777-5600 Telephone
(913) 777-5601 Facsimile

COUNSEL FOR PETITIONERS,
TAIWAN SEMICONDUCTOR
MANUFACTURING COMPANY LTD. AND
APPLE INC.